

PRIMER FOR METALLIZING SUBSTRATE SURFACES

ABSTRACT OF THE DISCLOSURE

A primer for the metallization of substrate surfaces by chemical reduction, comprising a) from about 3 to about 40% by weight of a film or matrix former, b) from about 0.1 to about 15% by weight of an additive having a molecular mass of 500 to 20,000, c) from about 0.1 to about 15% by weight of an ionic and/or colloidal metal or its organometallic covalent compound or complex compound with organic ligands, d) from about 0.5 to about 30% by weight of an organic and/or inorganic filler, e) from about 0.05 to about 5% by weight of a hydrophilic swelling material comprising finely divided particles containing silanol groups and/or partly modified silanol groups having a diameter of from 7 to 40 nm and a specific surface area of 50 to 380 m<sup>2</sup>/g, and f) from about 50 to about 90% by weight of organic solvents, in which all amounts by weight being based on the overall primer formulation, offers advantages at low bath loadings.